MA3X153 (MA153), MA3X153A (MA153A)

Silicon epitaxial planar type

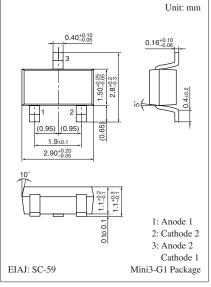
For switching circuits

■ Features

- Small terminal capacitance C_t
- Two diodes are connected in series in the package

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit
Reverse voltage	MA3X153	V_R	40	V
	MA3X153A		80	
Maximum peak	MA3X153	V_{RM}	40	V
reverse voltage	MA3X153A		80	
Forward current	Single	I_F	100	mA
	Series		65	
Peak forward	Single	I_{FM}	200	mA
current	Series		130	
Junction temperature		T_{j}	150	°C
Storage temperature		T_{stg}	-55 to +150	°C

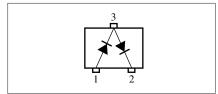


Marking Symbol

• MA3X153: MC

• MA3X153A: MP

Internal Connection

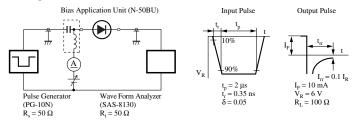


■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

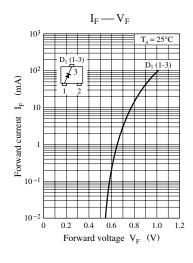
Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage		V_F	$I_F = 100 \text{ mA}$			1.2	V
Reverse voltage	MA3X153	V _R	$I_R = 100 \mu A$	40			V
	MA3X153A			80			
Reverse current	MA3X153	I_R	$V_R = 40 \text{ V}$			100	nA
	MA3X153A		$V_R = 75 \text{ V}$			100	
Terminal capacitance		C _t	$V_R = 0 V, f = 1 MHz$			5.0	pF
Reverse recovery time *	3	t _{rr} *1	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$		150		ns
		t _{rr} *2	$I_{rr} = 0.1 I_R, R_L = 100 \Omega$		9		ns

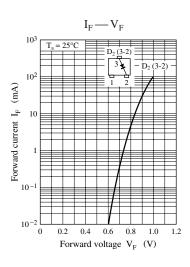
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

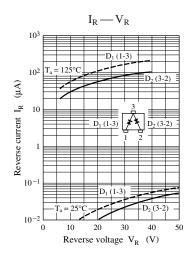
- 2. Absolute frequency of input and output is 100 MHz.
- 3. *1: Between pins 2 and 3
 - *2: Between pins 1 and 3
 - *3: t_{rr} measurement circuit

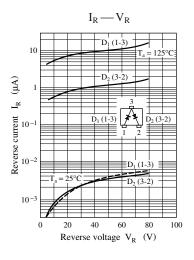


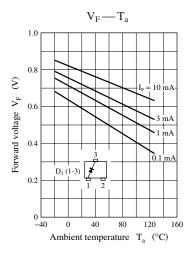
Note) The part numbers in the parenthesis show conventional part number.

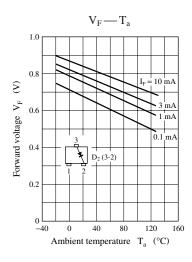


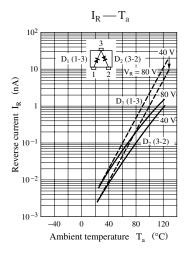


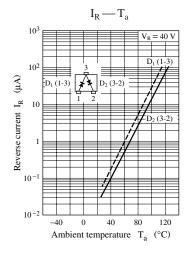


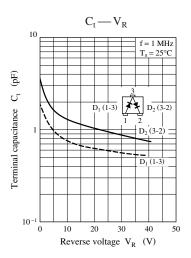












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